

Model JFP PP5-6 SERIES

FLIP CHIP DIE BONDER



APPLICATIONS:

- Pick & Place
- Flip Chip assembly
- Very small and large component
- MEMS, MMICS, IR sensor, opto, laser diode...
- Thermo-sonic die bonding
- Reflow, thermal cycle
- Eutectic thermo cycle
- Wafer sorter up to 8"
- Dispenser for epoxy & solder paste
- Stamping

The JFP PP5 is most versatile semi automatic Flip-Chip platform. It can be used in a wide field of applications such as; Standard IC; MMIC; MEMS; VECEL....

It achieves maximum accuracy placement using high quality optical device. Flip feature will allow a perfect alignment of parts and substrate, mixing both video pictures with a placement @ < **3 μ m @ 3 sigma**.

The PP5 series provide customers with the best cost / performance system on the market

Our proven expertise in bonding application effectively provides the technology and support to help our customers. A robust, and reliable mechanical concept, designed to be external vibration free. The PP5 is user friendly, flexible and requires minimal training to operate.

Specifications	
Model:	Flip Chip Die Bonder PP5-6 Pick & Place regular device Pick & Place flipped device
Motorized Tables:	X 250mm, Y 100mm / 1µm Manual Theta Joystick control: 2 speeds, adjustable
Pick & Place Head	Motorized Z Vacuum picking tool, 1/8 Minimum force: 10gr
Die size:	Minimum 200*200 µm Minimum 25mm*25mm
Substrate handled:	Up to 300x500 mm
Flip chip:	Up-looking camera Dual vision computing system
Vision:	Dual CCD Color camera 17" TFT panel Up-looking camera Dual video mixer for simultaneous alignment Target Crosshair generator
Light:	Direct and pen light, independent per camera
Ultrasonic Flip:	High Power multi frequency digital ultrasonic generator
Transducer:	Heavy duty 60Khz transducer
Alignment:	Place Mode direct for flip application 2 Ref point / Indexed XY at P&P position
Parameters:	Friendly Graphic user interface Force: 10gr to 6 Kgr programmable Bond Time: 1ms to 10sec programmable US Power: up to 30W programmable Scrub: XY amplitude and cycle programmable
Matrix:	Mapping / step and repeat / 2 ref point / Indexed
Operating System	Windows XP PRO
Utilities	100Vac to 230Vac / 500W Vacuum: 70%

Options

- Full inspection and customized criteria for sorting automation using vectorial recognition Cognex 8000.
- Eutectic Digital temperature profile control. 3 set points with nitrogen enclosure workholder
- Heated Work-Holder up to 8 inches (200mm)
- Double micro jet hot gas
- Rework BGA & Flip chip with solder removal module
- Oven C4 compatible
- Heavy duty bond head, 3 ranges Programmable up to 15Kg
- Piezzo driven micro gripper pick up head
- Dispenser
- Stamping
- UV insulator